

TAB 11: TECHNOLOGY ADMINISTRATION

Technology Administration Activities with China

Activities under TA_MOST Agreement (2003)

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| October 2003 | Under Secretary Phil Bond has a short bi-lateral meeting with MOST Vice Minister Liu Yanhua before starting the first China-U.S. Standards Workshop sponsored by TA, ITA, and Ministry of Science and Technology (MOST). U/S Bond discussed the idea of having a pilot test in which one school in the United States can have a web link with students in another school in China and exchange ideas and culture through computer communication. |
| October 2003 | U/S Bond attended a China-U.S. Standards Workshop held in Beijing. U/S Bond stated that NIST remains interested in working with China as it meets its WTO obligations and that NIST has tentatively scheduled an APEC training session for representatives of WTO in December 2004. China Vice Minister Liu provided a 4-point proposal to: (1) strengthen regular exchange between the parties to strengthen communication and understanding; (2) hold China-U.S workshops on standards; (3) strengthen the two parties' cooperation with respect to standardization; and (4) jointly work for increasing the two parties' status and influence in the ISO. |
| October 2003 | U/S Bond participated in a bilateral meeting with the General Administration of Quality Supervision Inspection and Quarantine and the Ministry of Information and Industry (AQSIQ). U/S Bond addressed the two Chinese mandatory national related to Wireless Area Networks (WLAN) recently published on May 12 , 2003 and announced on July 9, 2003. |
| October 2003 | U/S Bond visits with Mr. Wee Theng Tan, President of Intel China and North Asia Managing Director responsible for Intel China and Korea. |
| October 2003 | U/S Bond met Mr. Ren Ranqi, Deputy Director of the Beijing Municipality Administrative Committee of the Zhongguancun Science Park, who presented us a briefing on the science park. |
| October 2003 | Phil Bond visited Raytek with Secretary Evans' delegation where they met with Jimmy Hwong, President of Fluke China (parent of Raytek). Secretary Evans delivered brief |

remarks on manufacturing entrepreneurial efforts of U.S. SMEs doing business in China.

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| October 2003 | Phil Bond visited Hauwei Technologies (the only Chinese company during his trip was). Mr. Shu Quan Li, Huawei CEO, provided an excellent tour and briefing of the company. |
| October 2003 | Phil Bond attended the bilateral meeting with the Ministry of Information Industries (MII) and the State Council Informatization Office, which took place prior to the SCITO Roundtable. Secretary Evans raised three issues with MII Minister Wang: third generation (3G) technology development, government procurement of software, and wireless local area network (LAN) encryption standards. Evans stated that U.S. hopes that China would implement wireless LAN encryption standards that are uniform and appropriate. Wang responded that MII would first conduct a trial of 3G technology compatibility and interconnectivity and then will decide on the 3G standard for China. On government procurement, Wang noted China's efforts to promote informatization and encourage domestic development for domestic software industry while maintaining its WTO commitments. |
| October 2003 | U/S Bond visited the Shenzhen High-Tech Industrial Park (SHIP). MOST VM Liu recommended visiting this park to Phil Bond during his last visit to Washington in September 2003. SHIP Deputy Director Liu Zhong Pu provided a briefing about the Shenzhen High-Tech Industrial Park. |
| October 2003 | U/S Bond visited the Hong Kong Science and Technology Park. Dr. S.W.Cheng, Vice President of Business Development and Technology Support, provided a great tour of the facilities. |
| October 2003 | U/S Bond participated in a tour of the Cyberport in Hong Kong and meet with Francis Ho, Permanent Secretary of Commerce, Industry and Technology. |
| September 2003 Vice | D/S Samuel Bodman and U/S Bond meet with AQSIQ Minister Li Chuanqing during a visit of their delegation to Washington, DC. D/S Bodman and VM Li signed a Statement |

Of Intent for TA and AQSIQ to develop a protocol for the purpose of promoting cooperation in the fields of metrology, standards and related basic and applied sciences.

Activities under TA-MOST Agreement (2002)

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| December 2002 | The Secretary signs the Protocol Agreement on Cooperation in Civilian Industrial Technology and Scientific and Technical Information and Policy with the PRC Ministry of Science and Technology |
| September 2002 | Under Secretary Bond attended the World Electronics Forum in Beijing. Meetings were also held with the PRC Ministry of Science and Technology, SCITO, US-China Business Council, and MOFTEC. |
| August 2002 | Deputy Under Secretary Ben Wu leads an IPR delegation of experts to hold a series of workshops in partnership with the PRC Ministry of Science and Technology in Beijing, Dalian, and Shenzhen, China. Meetings were also held with AQSIQ, SCITO, and the American Chamber of Commerce. |
| August 2002 | TA witnessed the University of Maryland-MOST signing agreement for the US-China Technology Park in College Park, MD. Initiated as an activity under TA's agreement with MOST, the park is designed to promote technology collaboration between U.S. and Chinese universities and businesses. |
| August 2002 | Under Secretary Bond and Vice Minister Liu hold their first quarterly meeting in Washington, DC. Topics of discussion include |
| April 2002 | Bilateral Meeting between Phillip J. Bond, Chief of Staff and Under Secretary for Technology, and XU Guanhua, Minister of Science and Technology (MOST). Participants included representatives of U.S. high-tech companies and MOST. Discussions resulted in agreement to have quarterly senior level meetings between U/S and Vice |

Minister, and to expand cooperation on a range of technology and innovation issues, including standards, intellectual property rights, university and industry linkages, development of venture capital, etc.

April 2002

TA and MOST co-chair in Beijing the first in a series of “Innovation and Entrepreneurship Roundtables” on University-Industry Partnerships. Representatives of U.S. and Chinese high-tech companies and Chinese universities joined Chief of Staff and Under Secretary for Technology, Phillip J. Bond, and SHI Dinghuan, MOST Secretary-General, in discussing the growth of university-industry collaboration in China and obstacles, such as university teaching demands, visas, technology management practices, etc.

April 2002

Chief of Staff and Under Secretary for Technology, Phillip J. Bond, leads a group of U.S. company representatives in meeting with Shanghai’s Vice Mayor for Technology. They agreed to examine ways to expand U.S.-China Technology collaboration and Under Secretary Bond agreed to hold regular DOC consultations with the Vice Mayor on technology and innovation issues.

April 2002

TA Deputy Under Secretary for Technology, Benjamin Wu, participates in opening of University of Maryland-MOST Technology Park in College Park. Initiated as an activity under TA’s agreement with MOST, the park is designed to promote technology collaboration between U.S. and Chinese universities and businesses.

Feb 2002

Phillip J. Bond, Chief of Staff and Under Secretary for Technology, meets in Washington, D.C. with MOST Vice Minister Ma to review TA-MOST collaboration.